PCN # 1786

DATE: June 20, 2018

EXPECTED PCN SHIP DATE: June 20, 2018



Quality Assurance 160 Rio Robles San Jose, CA 95134

www.maximintegrated.com

	PROCESS CHANGE NOTICE
X	PRODUCT CHANGE NOTICE

THAT MAY AFFECT THE FOLLOWING CATEGORIES:

DESIGN WAFER FAB ASSEMBLY TEST X ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE

Ordering P/N: (See PN listing XLS in PCN ZIP file)			
CHANGE FROM: -	CHANGE TO: -		
Datasheet update for MAX30205 (Temperature Sensor), see			
attachment			
Under "Absolute Maximum Ratings" section (page 2):			
Lead Temperature (soldering, 10s) +300°C (LT)	LT/ST: +220°C		
Soldering Temperature (reflow) +260°C (ST)			
Under "Pin Description" section (page 6):			
Name/Function: EP/Connect EP to GND	Leave EP unconnected		
JUSTIFICATION: -			
High lead temperature or soldering temperature will cause the device to fail the +/- 0.1 °C accuracy spec.			

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Connect EP to ground will increase thermal losses to the PC board so temperature reading is less accurate.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

or

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative

Nasser AliChaouche, PCN Coordinator 408-601-5660 / pcn.coordinator@maximintegrated.com

Document Title: Product Change Notice - Notification Only

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